

Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

E·XFI

Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	5
Program Memory Size	1.5KB (1K x 12)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	41 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	8-VDFN Exposed Pad
Supplier Device Package	8-DFN (3x3)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic12lc509at-04i-mf

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

1.0 GENERAL DESCRIPTION

The PIC12C5XX from Microchip Technology is a family of low-cost, high performance, 8-bit, fully static, EEPROM/EPROM/ROM-based CMOS microcontrollers. It employs a RISC architecture with only 33 single word/single cycle instructions. All instructions are single cycle (1 μ s) except for program branches which take two cycles. The PIC12C5XX delivers performance an order of magnitude higher than its competitors in the same price category. The 12-bit wide instructions are highly symmetrical resulting in 2:1 code compression over other 8-bit microcontrollers in its class. The easy to use and easy to remember instruction set reduces development time significantly.

The PIC12C5XX products are equipped with special features that reduce system cost and power requirements. The Power-On Reset (POR) and Device Reset Timer (DRT) eliminate the need for external reset circuitry. There are four oscillator configurations to choose from, including INTRC internal oscillator mode and the power-saving LP (Low Power) oscillator mode. Power saving SLEEP mode, Watchdog Timer and code protection features also improve system cost, power and reliability.

The PIC12C5XX are available in the cost-effective One-Time-Programmable (OTP) versions which are suitable for production in any volume. The customer can take full advantage of Microchip's price leadership in OTP microcontrollers while benefiting from the OTP's flexibility.

The PIC12C5XX products are supported by a full-featured macro assembler, a software simulator, an in-circuit emulator, a 'C' compiler, fuzzy logic support tools, a low-cost development programmer, and a full featured programmer. All the tools are supported on IBM[®] PC and compatible machines.

1.1 Applications

The PIC12C5XX series fits perfectly in applications ranging from personal care appliances and security systems to low-power remote transmitters/receivers. The EPROM technology makes customizing application programs (transmitter codes, appliance settings, receiver frequencies. etc.) extremely fast and convenient, while the EEPROM data memory technology allows for the changing of calibration factors and security codes. The small footprint packages, for through hole or surface mounting, make this microcontroller series perfect for applications with space limitations. Low-cost, low-power, high performance, ease of use and I/O flexibility make the PIC12C5XX series very versatile even in areas where no microcontroller use has been considered before (e.g., timer functions, replacement of "glue" logic and PLD's in larger systems, coprocessor applications).

NOTES:

4.5 <u>OSCCAL Register</u>

The Oscillator Calibration (OSCCAL) register is used to calibrate the internal 4 MHz oscillator. It contains four to six bits for calibration. Increasing the cal value increases the frequency. See Section 7.2.5 for more information on the internal oscillator.

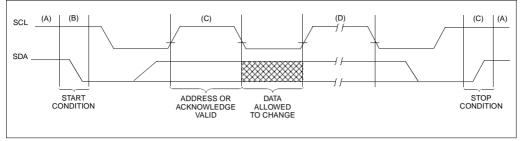
FIGURE 4-6: OSCCAL REGISTER (ADDRESS 05h) FOR PIC12C508 AND PIC12C509

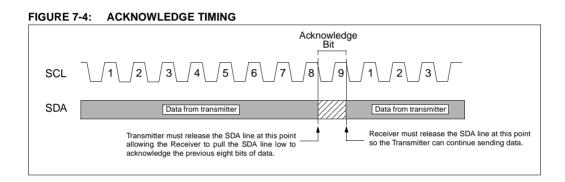
R/W-0	R/W-1	R/W-1	R/W-1	R/W-0	R/W-0	U-0	U-0	
CAL3	CAL2	CAL1	CAL0	-		—	—	R = Readable bit
bit7							bit0	 W = Writable bit U = Unimplemented bit, read as '0' n = Value at POR reset
bit 7-4:	bit 7-4: CAL<3:0>: Calibration							
bit 3-0: Unimplemented: Read as '0'								

FIGURE 4-7: OSCCAL REGISTER (ADDRESS 05h) FOR PIC12C508A/C509A/CR509A/12CE518/ 12CE519

CAL5 CAL4 CAL3 CAL2 CAL1 CAL0 — — R = Readable bit bit7 bit0 bit0 U = Writable bit U = Unimplemented bit, read en (10)	bit0 W = Writable bit		CAL0	CAL1	041.0			
U = Unimplemented bit,	Dito	bit0 W = Writ			CALZ	CAL3	CAL4	CAL5
- n = Value at POR reset	read as '0'	U = Unir read				•		bit7
bit 7-2: CAL<5:0>: Calibration		bit 7-2:						
bit 1-0: Unimplemented: Read as '0'		bit 1-0:						

FIGURE 7-3: DATA TRANSFER SEQUENCE ON THE SERIAL BUS





7.2 Device Addressing

After generating a START condition, the bus master transmits a control byte consisting of a slave address and a Read/Write bit that indicates what type of operation is to be performed. The slave address consists of a 4-bit device code (1010) followed by three don't care bits.

The last bit of the control byte determines the operation to be performed. When set to a one a read operation is selected, and when set to a zero a write operation is selected. (Figure 7-5). The bus is monitored for its corresponding slave address all the time. It generates an acknowledge bit if the slave address was true and it is not in a programming mode.

FIGURE 7-5: CONTROL BYTE FORMAT

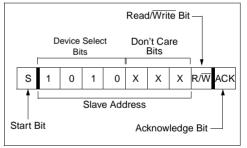
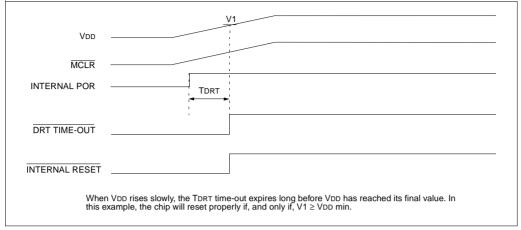


FIGURE 8-11: TIME-OUT SEQUENCE ON POWER-UP (MCLR TIED TO VDD): SLOW VDD RISE TIME



8.5 Device Reset Timer (DRT)

In the PIC12C5XX, DRT runs from RESET and varies based on oscillator selection (see Table 8-5.)

The DRT operates on an internal RC oscillator. The processor is kept in RESET as long as the DRT is active. The DRT delay allows VDD to rise above VDD min., and for the oscillator to stabilize.

Oscillator circuits based on crystals or ceramic resonators require a certain time after power-up to establish a stable oscillation. The on-chip DRT keeps the device in a RESET condition for approximately 18 ms after MCLR has reached a logic high (VIHMCLR) level. Thus, programming GP3/MCLR/VPP as MCLR and using an external RC network connected to the MCLR input is not required in most cases, allowing for savings in cost-sensitive and/or space restricted applications, as well as allowing the use of the GP3/MCLR/VPP pin as a general purpose input.

The Device Reset time delay will vary from chip to chip due to VDD, temperature, and process variation. See AC parameters for details.

The DRT will also be triggered upon a Watchdog Timer time-out. This is particularly important for applications using the WDT to wake from SLEEP mode automatically.

8.6 Watchdog Timer (WDT)

The Watchdog Timer (WDT) is a free running on-chip RC oscillator which does not require any external components. This RC oscillator is separate from the external RC oscillator of the GP5/OSC1/CLKIN pin and the internal 4 MHz oscillator. That means that the WDT will run even if the main processor clock has been stopped, for example, by execution of a SLEEP instruction. During normal operation or SLEEP, a WDT reset or wake-up reset generates a device RESET.

The \overline{TO} bit (STATUS<4>) will be cleared upon a Watchdog Timer reset.

The WDT can be permanently disabled by programming the configuration bit WDTE as a '0' (Section 8.1). Refer to the PIC12C5XX Programming Specifications to determine how to access the configuration word.

TABLE 8-5: DRT (DEVICE RESET TIMER PERIOD)

Oscillator Configuration	POR Reset	Subsequent Resets
IntRC & ExtRC	18 ms (typical)	300 µs (typical)
XT & LP	18 ms (typical)	18 ms (typical)

ADDWF	Add W and f
Syntax:	[label] ADDWF f,d
Operands:	$\begin{array}{l} 0 \leq f \leq 31 \\ d \in \left[0,1 \right] \end{array}$
Operation:	(W) + (f) \rightarrow (dest)
Status Affected:	C, DC, Z
Encoding:	0001 11df ffff
Description:	Add the contents of the W register and register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is '1' the result is stored back in register 'f'.
Words:	1
Cycles:	1
Example:	ADDWF FSR, 0
Before Instru W = FSR = After Instruct W = FSR =	0x17 0xC2 tion 0xD9

ANDWF	AND W with f
Syntax:	[label] ANDWF f,d
Operands:	$\begin{array}{l} 0 \leq f \leq 31 \\ d \in \left[0,1 \right] \end{array}$
Operation:	(W) .AND. (f) \rightarrow (dest)
Status Affected:	Z
Encoding:	0001 01df ffff
Description:	The contents of the W register are AND'ed with register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is '1' the result is stored back in register 'f'.
Words:	1
Cycles:	1
Example:	ANDWF FSR, 1
Before Instru W = FSR =	0x17
After Instruct W = FSR =	0x17

ANDLW	And literal with W
Syntax:	[<i>label</i>] ANDLW k
Operands:	$0 \le k \le 255$
Operation:	(W).AND. (k) \rightarrow (W)
Status Affected:	Z
Encoding:	1110 kkkk kkkk
Description:	The contents of the W register are AND'ed with the eight-bit literal 'k'. The result is placed in the W register.
Words:	1
Cycles:	1
Example:	ANDLW 0x5F
Before Instru W =	iction 0xA3
After Instruct W =	tion 0x03

BCF	Bit Clear	f		
Syntax:	[label] E	BCF f,b)	
Operands:	$\begin{array}{l} 0 \leq f \leq 31 \\ 0 \leq b \leq 7 \end{array}$			
Operation:	$0 \rightarrow (f < b;$	>)		
Status Affected:	None			
Encoding:	0100	bbbf	ffff	
Description:	Bit 'b' in re	gister 'f' is	cleared.	
Words:	1			
Cycles:	1			
Example:	BCF	FLAG_REC	3, 7	
Before Instruction FLAG_REG = 0xC7				
After Instruction FLAG_REG = 0x47				

BSF	Bit Set f	BTFSS	Bit Test f, Skip if Set		
Syntax:	[label] BSF f,b	Syntax:	[label] BTFSS f,b		
Operands:	$0 \le f \le 31$ $0 \le b \le 7$	Operands:	$0 \le f \le 31$ $0 \le b < 7$		
Operation:	$1 \rightarrow (f < b >)$	Operation:	skip if (f) = 1		
Status Affected:	None	Status Affected:	None		
Encoding:	0101 bbbf ffff	Encoding:	0111 bbbf ffff		
Description:	Bit 'b' in register 'f' is set.	Description:	If bit 'b' in register 'f' is '1' then the next		
Words:	1		instruction is skipped.		
Cycles:	1		If bit 'b' is '1', then the next instruction fetched during the current instruction		
Example:	BSF FLAG_REG, 7		execution, is discarded and an NOP is		
Before Instru	uction		executed instead, making this a 2 cycle instruction.		
_	EG = 0x0A	Words:	1		
After Instruction FLAG REG = 0x8A		Cycles:	1(2)		
FLAG_K		Example:	HERE BTFSS FLAG,1 FALSE GOTO PROCESS_CODE		
BTFSC	Bit Test f, Skip if Clear		TRUE •		
Syntax:	[label] BTFSC f,b		•		
Operands:	$0 \le f \le 31$	Before Instr	uction		
	$0 \le b \le 7$	PC	= address (HERE)		
Operation:	skip if $(f < b >) = 0$	After Instruc			
Status Affected:	None	If FLAG PC	<1> = 0, = address (FALSE);		
Encoding:	0110 bbbf ffff	if FLAG<	<1> = 1,		
Description:	If bit 'b' in register 'f' is 0 then the next instruction is skipped.	PC	= address (TRUE)		
	If bit 'b' is 0 then the next instruction fetched during the current instruction execution is discarded, and an NOP is				

executed instead, making this a 2 cycle

BTFSC FLAG,1

address (HERE)

address (TRUE);

address(FALSE)

PROCESS_CODE

GOTO

٠ •

0, =

1, =

instruction.

1

1(2)

HERE

TRUE

Before Instruction PC

After Instruction if FLAG<1>

if FLAG<1>

PC

PC

FALSE

=

=

=

Words:

Cycles:

Example:

INCF	Increment f
Syntax:	[label] INCF f,d
Operands:	$\begin{array}{l} 0 \leq f \leq 31 \\ d \in \left[0,1\right] \end{array}$
Operation:	(f) + 1 \rightarrow (dest)
Status Affected:	Z
Encoding:	0010 10df ffff
Description:	The contents of register 'f' are incre- mented. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is placed back in register 'f'.
Words:	1
Cycles:	1
Example:	INCF CNT, 1
Before Instru CNT Z	= 0xFF = 0
After Instruct	
CNT Z	= 0x00 = 1
INCFSZ	Increment f, Skip if 0
Syntax:	[label] INCFSZ f,d
Operands:	$0 \le f \le 31$

Syntax:	[label] INCFSZ f,d
Operands:	$\begin{array}{l} 0 \leq f \leq 31 \\ d \in \ [0,1] \end{array}$
Operation:	(f) + 1 \rightarrow (dest), skip if result = 0
Status Affected:	None
Encoding:	0011 11df ffff
Description:	The contents of register 'f' are incre- mented. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is placed back in register 'f'. If the result is 0, then the next instruc- tion, which is already fetched, is dis- carded and an NOP is executed instead making it a two cycle instruc- tion.
Words:	1
Cycles:	1(2)
Example:	HERE INCFSZ CNT, 1 GOTO LOOP
	CONTINUE • •
Before Inst PC	ruction = address (HERE)
After Instru CNT if CNT PC if CNT PC	= CNT + 1;

IORLW	Inclusive OR literal with W
Syntax:	[<i>label</i>] IORLW k
Operands:	$0 \le k \le 255$
Operation:	(W) .OR. (k) \rightarrow (W)
Status Affected:	Z
Encoding:	1101 kkkk kkkk
Description:	The contents of the W register are OR'ed with the eight bit literal 'k'. The result is placed in the W register.
Words:	1
Cycles:	1
Example:	IORLW 0x35
Before Instru W =	uction 0x9A
After Instruc W = Z =	tion 0xBF 0

IORWF	Inclusive OR W with f
Syntax:	[label] IORWF f,d
Operands:	$\begin{array}{l} 0\leq f\leq 31\\ d\in \ [0,1] \end{array}$
Operation:	(W).OR. (f) \rightarrow (dest)
Status Affected	I: Z
Encoding:	0001 00df ffff
Description:	Inclusive OR the W register with regis- ter 'f'. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is placed back in register 'f'.
Words:	1
Cycles:	1
Example:	IORWF RESULT, 0
Before Inst RESUL W After Instru	LT = 0x13 = 0x91
RESUL W Z	

SWAPF	Swap Nibbles in f							
Syntax:	[label] SWAPF f,d							
Operands:	$\begin{array}{l} 0\leq f\leq 31\\ d\in \left[0,1\right] \end{array}$							
Operation:	$(f<3:0>) \rightarrow (dest<7:4>);$ $(f<7:4>) \rightarrow (dest<3:0>)$							
Status Affected:	None							
Encoding:	0011 10df ffff							
Description:	The upper and lower nibbles of register 'f' are exchanged. If 'd' is 0 the result is placed in W register. If 'd' is 1 the result is placed in register 'f'.							
Words:	1							
Cycles:	1							
Example	SWAPF REG1, 0							
Before Instru REG1	iction = 0xA5							
After Instruct REG1 W	tion = 0xA5 = 0X5A							

TRIS	Load TRIS Register					
Syntax:	[label] TRIS f					
Operands:	f = 6					
Operation:	(W) \rightarrow TRIS register f					
Status Affected:	None					
Encoding:	0000 0000 0fff					
Description:	TRIS register 'f' ($f = 6$) is loaded with the contents of the W register					
Words:	1					
Cycles:	1					
Example	TRIS GPIO					
Before Instru W	iction = 0XA5					
After Instruct TRIS						
Note: f = 6 f	or PIC12C5XX only.					

XORLW	Exclusiv	ve OR lite	ral with	w			
Syntax:	[<i>label</i>]	XORLW	k				
Operands:	$0 \le k \le 2$	55					
Operation:	(W) .XO	$R. k \to (W$	/)				
Status Affected:	Affected: Z						
Encoding:	1111	kkkk	kkkk				
Description:	The contents of the W register are XOR'ed with the eight bit literal 'k'. The result is placed in the W register.						
Words:	1						
Cycles:	1						
Example:	XORLW	0xAF					
Before Instru W =	uction 0xB5						
After Instruc W =	tion 0x1A						

XORWF	Exclusive OR W with f
Syntax:	[label] XORWF f,d
Operands:	$\begin{array}{l} 0 \leq f \leq 31 \\ d \in \ [0,1] \end{array}$
Operation:	(W) .XOR. (f) \rightarrow (dest)
Status Affected:	Z
Encoding:	0001 10df ffff
Description:	Exclusive OR the contents of the W register with register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'.
Words:	1
Cycles:	1
Example	XORWF REG,1
Before Instru REG W After Instruct REG	= 0xAF = 0xB5 ion = 0x1A
W	= 0xB5

11.2 DC CHARACTERISTICS:

PIC12C508/509 (Commercial, Industrial, Extended)

			rd Operati ng tempera	-	0°C ≤	TA ≤ +	s otherwise specified) 70°C (commercial)			
DC CHA	ARACTERISTICS	–40°C ≤ TA ≤ +85°C (industrial) –40°C ≤ TA ≤ +125°C (extended)								
		Operating voltage VDD range as described in DC spec Section 11.1 and Section 11.2.								
Param No.	Characteristic	Sym	Min	Тур†	Max	Units	Conditions			
NO.										
	Input Low Voltage	VIL								
D 000	•	VIL	Vee	-	0.01/	V				
D030	with TTL buffer		Vss	-	0.8V	V	4.5 < VDD ≤ 5.5V			
D031	with Coheritt Trigger huffer		Vee	-	0.15VDD 0.15VDD	V V	otherwise			
D031 D032	with Schmitt Trigger buffer MCLR, GP2/T0CKI (in EXTRC mode)		Vss Vss	-	0.15VDD 0.15VDD	V				
			VSS VSS	-	0.15VDD	v				
D033	OSC1 (EXTRC) ⁽¹⁾			-						
D033	OSC1 (in XT and LP)		Vss	-	0.3Vdd	V	Note1			
	Input High Voltage									
	I/O ports	VIH		-						
D040	with TTL buffer	Vss	2.0V	-	Vdd	V	$4.5 \leq VDD \leq 5.5V$			
D040A			0.25VDD+ 0.8V	-	Vdd	V	otherwise			
D041	with Schmitt Trigger buffer		0.85VDD	-	VDD	v	For entire VDD range			
D042	MCLR/GP2/T0CKI		0.85VDD	-	VDD	v				
-			0.7VDD	-	VDD	V	Note1			
D043	OSC1 (in EXTRC mode)		0.85VDD	-	VDD	V				
D070	GPIO weak pull-up current	IPUR	50	250	400	μA	VDD = 5V, VPIN = VSS			
	Input Leakage Current ^(2, 3)					1.	For VDD ≤5.5V			
D060	I/O ports	١L	-1	0.5	<u>+</u> 1	μΑ	Vss ≤ VPIN ≤ VDD, Pin at hi-impedance			
D061	MCLR, GP2/T0CKI		20	130	250	μA	$V_{PIN} = V_{SS} + 0.25 V^{(2)}$			
2001				0.5	+5	μΑ	VPIN = VDD			
D063	OSC1		-3	0.5	+3	μΑ	$Vss \le VPIN \le VDD$,			
							XT and LP options			
	Output Low Voltage									
D080	I/O ports/CLKOUT	Vol	-	-	0.6	V	IOL = 8.7 mA, VDD = 4.5V			
	Output High Voltage									
D090	I/O ports/CLKOUT (3)	Voh	Vdd - 0.7	-	-	V	IOH = -5.4 mA, VDD = 4.5V			
	Capacitive Loading Specs on									
	Output Pins									
D100	OSC2 pin	Cosc2	-	-	15	pF	In XT and LP modes when external clock is used to drive OSC1.			
D101	All I/O pins	Cio	-	-	50	pF				
	Data in "Typ" column is at 51/ 25°C ur						l			

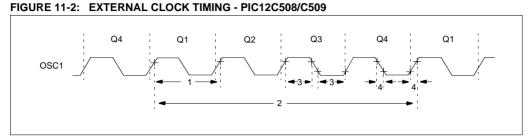
† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In EXTRC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC12C5XX be driven with external clock in RC mode.

2: The leakage current on the MCLR pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as coming out of the pin.

11.4 Timing Diagrams and Specifications





AC Chara	cteristics	$ \begin{array}{ll} \mbox{Standard Operating Conditions (unless otherwise specified)} \\ \mbox{Operating Temperature} & 0^{\circ}C \leq Ta \leq +70^{\circ}C \mbox{ (commercial)}, \\ -40^{\circ}C \leq Ta \leq +85^{\circ}C \mbox{ (industrial)}, \\ -40^{\circ}C \leq Ta \leq +125^{\circ}C \mbox{ (extended)} \\ \mbox{Operating Voltage VDD range is described in Section 11.1} \end{array} $							
Parameter No.	Sym	Characteristic	Min	Typ ⁽¹⁾	Мах	Units	Conditions		
	Fosc	External CLKIN Frequency ⁽²⁾							
			DC	—	4	MHz	XT osc mode		
			DC	—	200	kHz	LP osc mode		
		Oscillator Frequency ⁽²⁾							
			0.1	_	4	MHz	XT osc mode		
			DC	—	200	kHz	LP osc mode		
1	Tosc	External CLKIN Period ⁽²⁾	250	—	_	ns	EXTRC osc mode		
			250	_	_	ns	XT osc mode		
			5	—	—	ms	LP osc mode		
		Oscillator Period ⁽²⁾	250	_	_	ns	EXTRC osc mode		
			250	_	10,000	ns	XT osc mode		
			5	—	—	ms	LP osc mode		
2	Тсу	Instruction Cycle Time ⁽³⁾	—	4/Fosc	—				
3	TosL, TosH	Clock in (OSC1) Low or High Time	50*	—	—	ns	XT oscillator		
			2*	_	—	ms	LP oscillator		
4	TosR, TosF	Clock in (OSC1) Rise or Fall Time	—	-	25*	ns	XT oscillator		
			—	—	50*	ns	LP oscillator		

* These parameters are characterized but not tested.

Note 1: Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

2: All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.

3: Instruction cycle period (TCY) equals four times the input oscillator time base period.

FIGURE 11-5: TIMER0 CLOCK TIMINGS - PIC12C508/C509

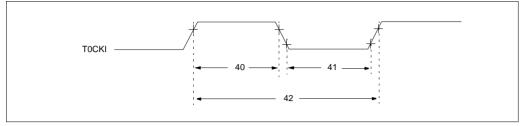


TABLE 11-7: TIMER0 CLOCK REQUIREMENTS - PIC12C508/C509

AC	Charao							
Parameter No.	Sym	Characteristic	•	Min	Тур ⁽¹⁾	Max	Units	Conditions
40	Tt0H	T0CKI High Pulse Width - No Prescaler		0.5 TCY + 20*	-	_	ns	
			- With Prescaler	10*	—	—	ns	
41	Tt0L	T0CKI Low Pulse W	/idth - No Prescaler	0.5 TCY + 20*	—	—	ns	
			- With Prescaler	10*	_	—	ns	
42	Tt0P	T0CKI Period		20 or <u>Tcy + 40</u> * N	_	_	ns	Whichever is greater. N = Prescale Value (1, 2, 4,, 256)

* These parameters are characterized but not tested.

Note 1: Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

13.2 DC CHARACTERISTICS:

PIC12LC508A/509A (Commercial, Industrial) PIC12LCE518/519 (Commercial, Industrial) PIC12LCR509A (Commercial, Industrial)

	DC Characteristics Power Supply Pins	$\begin{array}{ll} \mbox{Standard Operating Conditions (unless otherwise specified)} \\ \mbox{Operating Temperature} & 0^{\circ}\mbox{C} \leq \mbox{TA} \leq +70^{\circ}\mbox{C} \mbox{ (commercial)} \\ -40^{\circ}\mbox{C} \leq \mbox{TA} \leq +85^{\circ}\mbox{C} \mbox{ (industrial)} \end{array}$					
Parm No.	Characteristic	Sym	Min	Typ ⁽¹⁾	Max	Units	Conditions
D001	Supply Voltage	Vdd	2.5		5.5	V	Fosc = DC to 4 MHz (Commercial/ Industrial)
D002	RAM Data Retention Voltage ⁽²⁾	Vdr		1.5*		V	Device in SLEEP mode
D003	VDD Start Voltage to ensure Power-on Reset	VPOR		Vss		V	See section on Power-on Reset for details
D004	VDD Rise Rate to ensure Power-on Reset	SVDD	0.05*			V/ms	See section on Power-on Reset for details
D010	Supply Current ⁽³⁾	IDD	—	0.4	0.8	mA	XT and EXTRC options (Note 4) Fosc = 4 MHz, VDD = 2.5V
D010C			-	0.4	0.8	mA	INTRC Option Fosc = 4 MHz, VDD = 2.5V
D010A			-	15	23	μA	LP OPTION, Commercial Temperature Fosc = 32 kHz, VDD = 2.5V, WDT disabled
			-	15	31	μA	LP OPTION, Industrial Temperature Fosc = 32 kHz, VDD = 2.5V, WDT disabled
D020	Power-Down Current (5)	IPD					
D021 D021B				0.2 0.2	3 4	μΑ μΑ	VDD = 2.5V, Commercial VDD = 2.5V, Industrial
		ΔIWDT	-	2.0 2.0	4	mA mA	VDD = 2.5V, Commercial VDD = 2.5V, Industrial

* These parameters are characterized but not tested.

Note 1: Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

- 2: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.
- 3: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern, and temperature also have an impact on the current consumption.
 - a) The test conditions for all IDD measurements in active operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to Vss, TOCKI = VDD, MCLR = VDD; WDT enabled/disabled as specified.
 - b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode.
- 4: Does not include current through Rext. The current through the resistor can be estimated by the formula: IR = VDD/2Rext (mA) with Rext in kOhm.
- 5: The power down current in SLEEP mode does not depend on the oscillator type. Power down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or Vss.

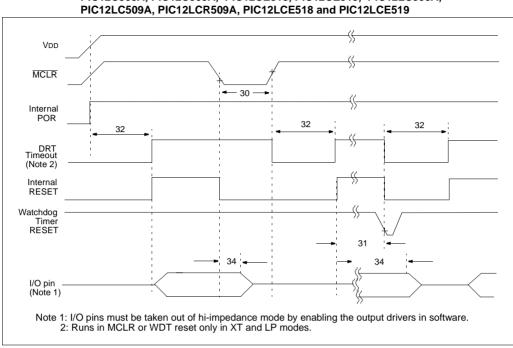


FIGURE 13-4: RESET, WATCHDOG TIMER, AND DEVICE RESET TIMER TIMING -PIC12C508A, PIC12C509A, PIC12CE518, PIC12CE519, PIC12LC508A, PIC12LC509A, PIC12LCR509A, PIC12LCE518 and PIC12LCE519

TABLE 13-5: RESET, WATCHDOG TIMER, AND DEVICE RESET TIMER - PIC12C508A, PIC12C509A, PIC12CE518, PIC12CE519, PIC12LC508A, PIC12LC509A, PIC12LCR509A, PIC12LCE518 and PIC12LCE519

AC Charact	teristics	$ \begin{array}{ll} \mbox{Standard Operating Conditions (unless otherwise specified)} \\ \mbox{Operating Temperature} & 0^{\circ}C \leq TA \leq +70^{\circ}C \mbox{ (commercial)} \\ & -40^{\circ}C \leq TA \leq +85^{\circ}C \mbox{ (industrial)} \\ & -40^{\circ}C \leq TA \leq +125^{\circ}C \mbox{ (extended)} \\ \mbox{Operating Voltage VDD range is described in Section 13.1} \end{array} $					
Parameter No.	Sym	Characteristic	Min	Typ ⁽¹⁾	Max	Units	Conditions
30	TmcL	MCLR Pulse Width (low)	2000*			ns	VDD = 5 V
31	Twdt	Watchdog Timer Time-out Period (No Prescaler)	9*	18*	30*	ms	VDD = 5 V (Commercial)
32	TDRT	Device Reset Timer Period ⁽²⁾	9*	18*	30*	ms	VDD = 5 V (Commercial)
34	Tioz	I/O Hi-impedance from MCLR Low	—	_	2000*	ns	

* These parameters are characterized but not tested.

Note 1: Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 2: See Table 13-6.

Oscillator	Frequency	VDD =3.0V	VDD = 5.5V		
External RC	4 MHz	240 µA*	800 µA*		
Internal RC	4 MHz	320 µA	800 µA		
XT	4 MHz	300 µA	800 µA		
LP	32 KHz	19 µA	50 µA		

TABLE 14-1: DYNAMIC IDD (TYPICAL) - WDT ENABLED, 25°C

*Does not include current through external R&C.

FIGURE 14-3: TYPICAL IDD VS. VDD (WDT DIS, 25°C, FREQUENCY

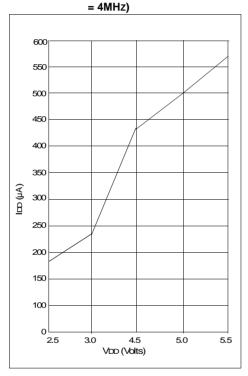
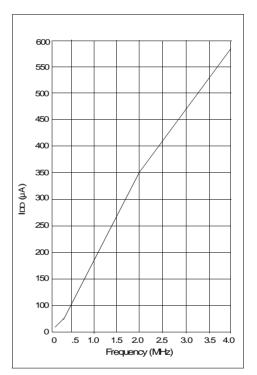
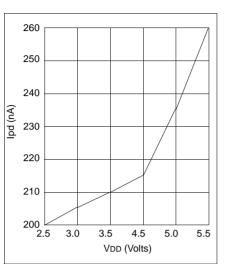


FIGURE 14-4: TYPICAL IDD VS. FREQUENCY (WDT DIS, 25°C, VDD = 5.5V)





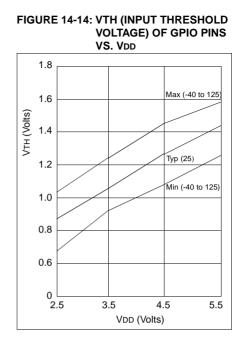
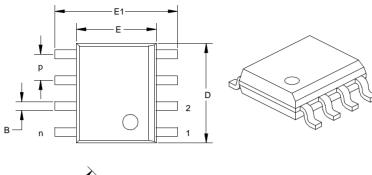
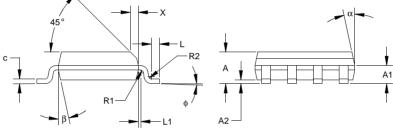


FIGURE 14-13: TYPICAL IPD VS. VDD, WATCHDOG DISABLED (25°C)

Package Type: K04-057 8-Lead Plastic Small Outline (SN) - Narrow, 150 mil





Units		INCHES*			MILLIMETERS			
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX	
Pitch	р		0.050			1.27		
Number of Pins	n		8			8		
Overall Pack. Height	A	0.054	0.061	0.069	1.37	1.56	1.75	
Shoulder Height	A1	0.027	0.035	0.044	0.69	0.90	1.11	
Standoff	A2	0.004	0.007	0.010	0.10	0.18	0.25	
Molded Package Length	D‡	0.189	0.193	0.196	4.80	4.89	4.98	
Molded Package Width	E‡	0.150	0.154	0.157	3.81	3.90	3.99	
Outside Dimension	E1	0.229	0.237	0.244	5.82	6.01	6.20	
Chamfer Distance	х	0.010	0.015	0.020	0.25	0.38	0.51	
Shoulder Radius	R1	0.005	0.005	0.010	0.13	0.13	0.25	
Gull Wing Radius	R2	0.005	0.005	0.010	0.13	0.13	0.25	
Foot Length	L	0.011	0.016	0.021	0.28	0.41	0.53	
Foot Angle	φ	0	4	8	0	4	8	
Radius Centerline	L1	0.000	0.005	0.010	0.00	0.13	0.25	
Lead Thickness	с	0.008	0.009	0.010	0.19	0.22	0.25	
Lower Lead Width	B [†]	0.014	0.017	0.020	0.36	0.43	0.51	
Mold Draft Angle Top	α	0	12	15	0	12	15	
Mold Draft Angle Bottom	β	0	12	15	0	12	15	

* Controlling Parameter.

- [†] Dimension "B" does not include dam-bar protrusions. Dam-bar protrusions shall not exceed 0.003" (0.076 mm) per side or 0.006" (0.152 mm) more than dimension "B."
- [‡] Dimensions "D" and "E" do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.010" (0.254 mm) per side or 0.020" (0.508 mm) more than dimensions "D" or "E."

ON-LINE SUPPORT

Microchip provides on-line support on the Microchip World Wide Web (WWW) site.

The web site is used by Microchip as a means to make files and information easily available to customers. To view the site, the user must have access to the Internet and a web browser, such as Netscape or Microsoft Explorer. Files are also available for FTP download from our FTP site.

Connecting to the Microchip Internet Web Site

The Microchip web site is available by using your favorite Internet browser to attach to:

www.microchip.com

The file transfer site is available by using an FTP service to connect to:

ftp://ftp.microchip.com

The web site and file transfer site provide a variety of services. Users may download files for the latest Development Tools, Data Sheets, Application Notes, User's Guides, Articles and Sample Programs. A variety of Microchip specific business information is also available, including listings of Microchip sales offices, distributors and factory representatives. Other data available for consideration is:

- Latest Microchip Press Releases
- Technical Support Section with Frequently Asked
 Questions
- Design Tips
- Device Errata
- Job Postings
- Microchip Consultant Program Member Listing
- Links to other useful web sites related to Microchip Products
- Conferences for products, Development Systems, technical information and more
- · Listing of seminars and events

Systems Information and Upgrade Hot Line

The Systems Information and Upgrade Line provides system users a listing of the latest versions of all of Microchip's development systems software products. Plus, this line provides information on how customers can receive any currently available upgrade kits.The Hot Line Numbers are:

1-800-755-2345 for U.S. and most of Canada, and

1-602-786-7302 for the rest of the world.

981103

Trademarks: The Microchip name, logo, PIC, PICmicro, PICSTART, PICMASTER and PRO MATE are registered trademarks of Microchip Technology Incorporated in the U.S.A. and other countries. *Flex*ROM, MPLAB and *fuzzy*-LAB are trademarks and SQTP is a service mark of Microchip in the U.S.A.

All other trademarks mentioned herein are the property of their respective companies.



WORLDWIDE SALES AND SERVICE

AMERICAS

Corporate Office 2355 West Chandler Blvd. Chandler, AZ 85224-6199 Tel: 480-792-7200 Fax: 480-792-7277 Technical Support: 480-792-7627 Web Address: http://www.microchip.com

Rocky Mountain

2355 West Chandler Blvd. Chandler, AZ 85224-6199 Tel: 480-792-7966 Fax: 480-792-7456

Atlanta

500 Sugar Mill Road, Suite 200B Atlanta, GA 30350 Tel: 770-640-0034 Fax: 770-640-0307

Boston

2 Lan Drive, Suite 120 Westford, MA 01886 Tel: 978-692-3848 Fax: 978-692-3821

Chicago

333 Pierce Road, Suite 180 Itasca, IL 60143 Tel: 630-285-0071 Fax: 630-285-0075

Dallas

4570 Westgrove Drive, Suite 160 Addison, TX 75001 Tel: 972-818-7423 Fax: 972-818-2924

Detroit Tri-Atria Office Building

32255 Northwestern Highway, Suite 190 Farmington Hills, MI 48334 Tel: 248-538-2250 Fax: 248-538-2260 Kokomo

2767 S. Albright Road

Kokomo, Indiana 46902 Tel: 765-864-8360 Fax: 765-864-8387 Los Angeles

18201 Von Karman, Suite 1090 Irvine, CA 92612

Tel: 949-263-1888 Fax: 949-263-1338 New York

150 Motor Parkway, Suite 202 Hauppauge, NY 11788 Tel: 631-273-5305 Fax: 631-273-5335 San Jose

Microchip Technology Inc. 2107 North First Street, Suite 590 San Jose, CA 95131 Tel: 408-436-7950 Fax: 408-436-7955

Toronto

6285 Northam Drive, Suite 108 Mississauga, Ontario L4V 1X5, Canada Tel: 905-673-0699 Fax: 905-673-6509

ASIA/PACIFIC

Australia

Microchip Technology Australia Pty Ltd Suite 22, 41 Rawson Street Epping 2121, NSW Australia

Tel: 61-2-9868-6733 Fax: 61-2-9868-6755 China - Beijing

Microchip Technology Consulting (Shanghai) Co., Ltd., Beijing Liaison Office Unit 915 Bei Hai Wan Tai Bldg. No. 6 Chaoyangmen Beidajie Beijing, 100027, No. China Tel: 86-10-85282100 Fax: 86-10-85282104

China - Chengdu

Microchip Technology Consulting (Shanghai) Co., Ltd., Chengdu Liaison Office Rm. 2401, 24th Floor, Ming Xing Financial Tower No. 88 TIDU Street Chengdu 610016, China Tel: 86-28-6766200 Fax: 86-28-6766599

China - Fuzhou

Microchip Technology Consulting (Shanghai) Co., Ltd., Fuzhou Liaison Office Unit 28F, World Trade Plaza No. 71 Wusi Road Fuzhou 350001, China Tel: 86-591-7503506 Fax: 86-591-7503521 China - Shanghai

Microchip Technology Consulting (Shanghai) Co., Ltd. Room 701, Bldg. B Far East International Plaza No. 317 Xian Xia Road Shanghai, 200051 Tel: 86-21-6275-5700 Fax: 86-21-6275-5060

China - Shenzhen

Microchip Technology Consulting (Shanghai) Co., Ltd., Shenzhen Liaison Office Rm. 1315, 13/F, Shenzhen Kerry Centre, Renminnan Lu Shenzhen 518001, China Tel: 86-755-2350361 Fax: 86-755-2366086 Hong Kong Microchip Technology Hongkong Ltd. Unit 901-6, Tower 2, Metroplaza

223 Hing Fong Road Kwai Fong, N.T., Hong Kong Tel: 852-2401-1200 Fax: 852-2401-3431

India

Microchip Technology Inc. India Liaison Office **Divvasree Chambers** 1 Floor, Wing A (A3/A4) No. 11, O'Shaugnessey Road Bangalore, 560 025, India Tel: 91-80-2290061 Fax: 91-80-2290062

Japan

Microchip Technology Japan K.K. Benex S-1 6F 3-18-20, Shinyokohama Kohoku-Ku, Yokohama-shi Kanagawa, 222-0033, Japan Tel: 81-45-471- 6166 Fax: 81-45-471-6122 Korea Microchip Technology Korea 168-1, Youngbo Bldg. 3 Floor Samsung-Dong, Kangnam-Ku Seoul, Korea 135-882 Tel: 82-2-554-7200 Fax: 82-2-558-5934 Singapore Microchip Technology Singapore Pte Ltd. 200 Middle Road #07-02 Prime Centre Singapore, 188980 Tel: 65-334-8870 Fax: 65-334-8850 Taiwan Microchip Technology Taiwan 11F-3, No. 207 Tung Hua North Road Taipei, 105, Taiwan Tel: 886-2-2717-7175 Fax: 886-2-2545-0139

EUROPE

Denmark

Microchip Technology Nordic ApS **Regus Business Centre** Lautrup hoj 1-3 Ballerup DK-2750 Denmark Tel: 45 4420 9895 Fax: 45 4420 9910 France Microchip Technology SARL Parc d'Activite du Moulin de Massy 43 Rue du Saule Trapu Batiment A - ler Etage 91300 Massy, France Tel: 33-1-69-53-63-20 Fax: 33-1-69-30-90-79 Germany Microchip Technology GmbH

Gustav-Heinemann Ring 125 D-81739 Munich, Germany Tel: 49-89-627-144 0 Fax: 49-89-627-144-44 Italy

Microchip Technology SRL Centro Direzionale Colleoni Palazzo Taurus 1 V. Le Colleoni 1 20041 Agrate Brianza Milan, Italy Tel: 39-039-65791-1 Fax: 39-039-6899883

United Kinadom

Arizona Microchip Technology Ltd. 505 Eskdale Road Winnersh Triangle Wokingham Berkshire, England RG41 5TU Tel: 44 118 921 5869 Fax: 44-118 921-5820

01/18/02